

IN THE CLAIMS:

Please amend claims 1, 7, 13, and 31, and please cancel claims 18-30, as set forth below.

1 1. (Currently Amended) An apparatus comprising:
2 a conductive land disposed on a first component, the land having a permanent depression
3 shaped to receive a conductive bump extending from a second component; and
4 a layer of a conductive material disposed over the land and the depression, the conductive
5 material layer to form electrical contact with the conductive bump extending from
6 the second component and into the depression.

1 2. (Original) The apparatus of claim 1, wherein the conductive material
2 layer comprises an anisotropic conductive material.

1 3. (Original) The apparatus of claim 2, wherein the electrical contact with
2 the conductive bump of the second component is created by compression of the
3 anisotropic conductive material in a region overlying the depression.

1 4. (Original) The apparatus of claim 3, wherein the anisotropic material
2 comprises an adhesive material to physically attach the conductive bump of the second
3 component to the land.

1 5. (Original) The apparatus of claim 1, wherein the first component
2 comprises a package substrate and the second component comprises an integrated circuit
3 die.

1 6. (Original) The apparatus of claim 1, wherein the first component
2 comprises a circuit board and the second component comprises a package substrate.

1 7. (Currently Amended) An apparatus comprising:
2 a substrate;
3 a number of conductive lands disposed on the substrate, each of the lands having a
4 permanent depression shaped to receive one of a number of conductive bumps
5 extending from a component; and
6 a layer of an anisotropic conductive material disposed over each of the lands and
7 depressions, the anisotropic conductive material layer on each land to form
8 electrical contact with the mating one conductive bump extending from the
9 component and into the depression of that land.

1 8. (Original) The apparatus of claim 7, wherein the electrical contact with
2 the mating one conductive bump of the component is created by compression of the
3 anisotropic conductive material in a region overlying the depression of that land.

1 9. (Original) The apparatus of claim 8, wherein the anisotropic material on
2 each land comprises an adhesive material to physically attach the mating one conductive
3 bump of the component to the land.

1 10. (Original) The apparatus of claim 9, wherein the anisotropic conductive
2 material of each of the lands comprises a single sheet of material.

1 11. (Original) The apparatus of claim 7, wherein the substrate comprises a
2 package substrate and the component comprises an integrated circuit die.

1 12. (Original) The apparatus of claim 7, wherein the substrate comprises a
2 circuit board and the component comprises a package substrate.

1 13. (Currently Amended) An assembly comprising:
2 a first component, the first component having a number of conductive bumps arranged in
3 a pattern;
4 a second component, the second component having a number of lands arranged in a
5 pattern corresponding to the pattern of the leads, each of the lands having a
6 permanent depression shaped to receive a mating one of the number of leads; and
7 a sheet of anisotropic conductive material disposed between the first and second
8 components, the anisotropic conductive material to form electrical contact
9 between each land and its mating one conductive bump.

1 14. (Original) The assembly of claim 13, wherein the electrical contact
2 between each land and its mating conductive bump is created by compression of the
3 anisotropic conductive sheet in a region overlying the depression of that land.

1 15. (Original) The assembly of claim 14, wherein the anisotropic conductive
2 sheet comprises an adhesive material to physically attach each land to its mating one
3 conductive bump.

1 16. (Original) The assembly of claim 13, wherein the first component
2 comprises an integrated circuit die and the second component comprises a package
3 substrate.

1 17. (Original) The assembly of claim 13, wherein first component comprises
2 a package substrate and the second component comprises a circuit board.

Claims 18.-30. (Canceled)

1 31. (Currently Amended) A system comprising:

2 a memory; and

3 a processing device coupled with the memory, the processing device including

4 a die, the die having a number of conductive bumps arranged in a pattern,

5 a package substrate, the package substrate having a number of lands

6 arranged in a pattern corresponding to the pattern of the conductive

7 bumps, each of the lands having a permanent depression shaped to

8 receive a mating one of the conductive bumps, and

9 a sheet of anisotropic conductive material disposed between the die and

10 package substrate, the anisotropic conductive material to form

11 electrical contact between each land and its mating one conductive

12 bump.

1 32. (Original) The system of claim 31, wherein the electrical contact between

2 each land and its mating conductive bump is created by compression of the anisotropic

3 conductive sheet in a region overlying the depression of that land.

1 33. (Original) The system of claim 32, wherein the anisotropic conductive

2 sheet comprises an adhesive material to physically attach each land to its mating one

3 conductive bump.